



General Description

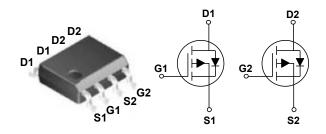
These P-Channel enhancement mode power field effect transistors are using trench MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
-60 V	105 mΩ	-4 A

Features

- $R_{DS(ON)} \le 105 m\Omega@V_{GS} = -10V$
- Fast Switching
- · Green Device Available
- Improved dv/dt Capability

SOP-8 Pin Configuration



Applications

- · MB / VGA / Vcore
- POL Applications
- · SMPS 2nd SR

Absolute Maximum Ratings T_C=25°C unless otherwise noted **Parameter Symbol** Rating Units V_{DS} Drain-Source Voltage -60 V_{GS} ٧ Gate-Source Voltage +20 I_D Drain Current - Continuous (T_A=25°C) -4 Α I_{DM} Drain Current - Pulsed (NOTE 1) -8 P_D Power Dissipation (T_A=25°C) 2.1 W T_{J} Operating Junction Temperature Range -55 to 150 ٥С Storage Temperature Range -55 to 150 T_{STG} οС Marking Code DS6809

Thermal Characteristics					
Symbol	Parameter	Тур.	Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		60	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V , I_D = -250uA	-60			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} = -60V , V_{GS} = 0V , T_{J} =25°C			-1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V_{GS} = -10V , I_D = -2A			105	mΩ
		V_{GS} = -4.5V , I_D = -1A			145	11122
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = -250 uA$	-1.2		-2.5	V
gfs	Forward Transconductance	V_{DS} = -10V , I_{D} = -1A		3		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V _{DS} = -30V , V _{GS} = -10V ,		10.4		
Q_gs	Gate-Source Charge	I _D = -2A		1.1		nC
Q_{gd}	Gate-Drain Charge	(NOTE 3)		2.7		
$T_{d(on)}$	Turn-On Delay Time	N		8		
T_r	Rise Time	V_{DD} = -30V , V_{GS} = -10V , R_{G} =6 Ω , I_{D} = -1A		15.4		nS
$T_{d(off)}$	Turn-Off Delay Time	(NOTE 3)		42.8		113
T_f	Fall Time			8.4		
C _{iss}	Input Capacitance			785		
C _{oss}	Output Capacitance	V _{DS} = -30V , V _{GS} = 0V , F= 1MHz		175		pF
C _{rss}	Reverse Transfer Capacitance			112		
R_g	Gate Resistance	V_{GS} = 0V , V_{DS} = 0V , F= 1MHz		27		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G = V _D = 0V,Force Current	-		-4	Α
I _{SM}	Pulsed Source Current	V _G - V _D - OV , Force Current			-8	Α
V_{SD}	Diode Forward Voltage	V_{GS} = 0V , I_{S} = -1A , T_{J} = 25 $^{\circ}$ C			-1	V
trr	Reverse Recovery Time	V _R = -50V , I _S = -1A ,		30		nS
Qrr	Reverse Recovery Charge	di/dt=100A/us		15		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.





Characteristics Curves

Fig.1 I_D vs. T_C

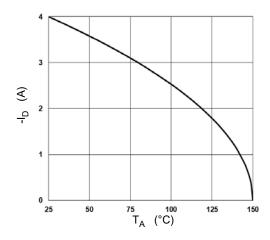


Fig.3 Normalized V_{th} vs. T_J

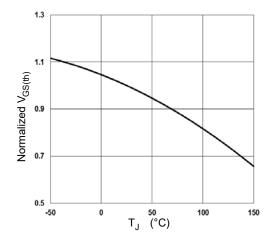


Fig.5 Normalized Transient Response

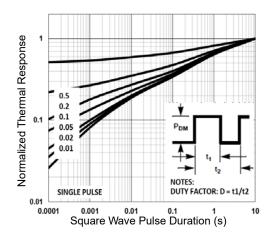


Fig.2 Normalized R_{DSON} vs. T_J

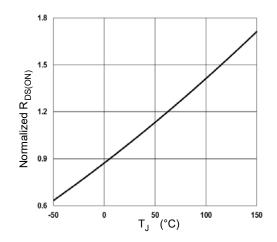


Fig.4 Gate Charge Waveform

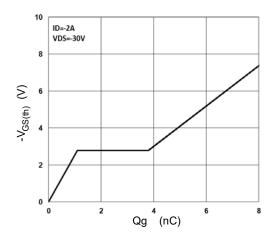
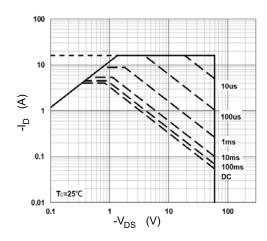


Fig.6 Maximum Safe Operation Area

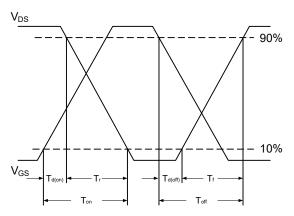




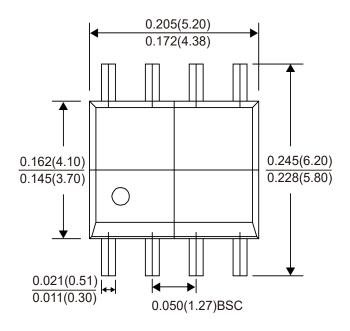


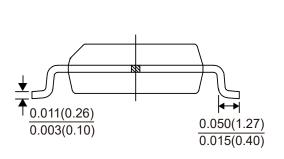
Characteristics Curves

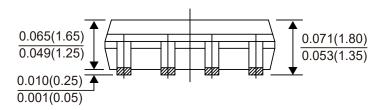
Fig.7 Switching Time Waveform



Package Outline Dimensions







SOP-8Dimensions in inches and (millimeters)



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